Device and Method for Stripping a Wafer from a Carrier

Abstract

Device for stripping a wafer from a carrier that is connected to the wafer by an interconnect layer with:

- a receiving means for accommodating the carrier-wafer combination consisting of the carrier and the wafer,
- a connection release means for breaking the connection provided by the interconnect layer between the carrier and the wafer, and
- stripping means for stripping the wafer from the carrier, or for stripping the carrier from the wafer,

the connection release means being made to work in a temperature range from 0 to 350°C, especially from 10 to 200°C, preferably from 20 to 80°C, and more preferably at ambient temperature.

Furthermore, the invention relates to a method for stripping a wafer from a carrier that is connected to the wafer by an interconnect layer with the following steps:

- accommodating the carrier-wafer combination consisting of the carrier and the wafer on a receiving means,
- breaking the connection provided by the interconnect layer between the carrier and the wafer by a connection release means, and
- stripping the wafer from the carrier, or for stripping the carrier from the wafer by stripping

means,

the connection release means working in a temperature range of up to 350°C, especially from 10 to 200°C, preferably from 20 to 80°C, and more preferably at ambient temperature.

In this regard, see Figure 1